# Digital Programmable Wafer Bake Plate

   QICEQUIP Programmable Bake Plate is a fully programmable digital hot plate designed specifically for baking silicon wafers. In manual operation simply set a target temperature and the unit will go to and hold that exact temperature to within ± 1 ° C. In the programmable mode routines can be stored in memory for instant recall and use. The stored routine will be run automatically, and exactly the same, again and again.

Programs can be simple or complex depending upon need. Multiple temperatures, temperature ramp rates if wanted, and dwell times can be stored. These programs can be written and stored in the remote controller provided with the unit, or the programs can be as simple or complex as needed when written by the user on a PC and run by that PC via theRS-485/RS-232 I/O port on the rear of the heater.

Features large circular milled-flat aluminum surface with temperature uniformity better than 1% across the heating surface. Designed specifically for working with 12" (304.8mm) diameter or smaller silicon wafers and other samples where temperature accuracy and surface uniformity are a must.
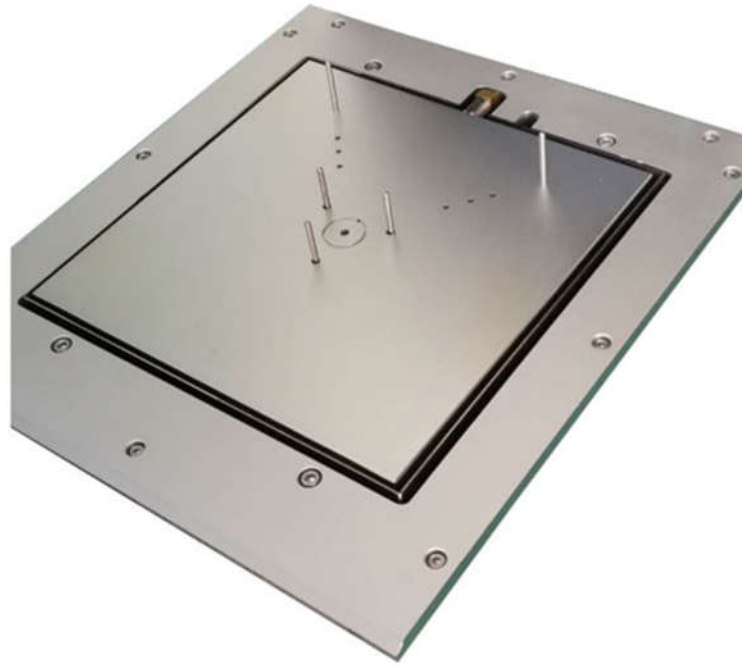
一：BENEFITS

1. performance and uniformity in a user-friendly and space saving design.

2. Compact design for minimized footprint

3. Enhanced logging

4. Cool touch exhausted hood

5. Smart Pins for programmable height control

6. Adjustable exhaust gate

7. Durable benchtop design also available in a flange/deck mountable configuration

8. an upper exhaust enclosure for process fume control.

二：BAKE HOOD DESIGN

1. All stainless-steel construction

2. Unique 2-layer design reduces exterior hood temperature

3. Exhausted hood for removal of process chemicals

4. Optional nitrogen purge inert bake environment

三：PROGRAMMABILITY

1. Full-color touchscreen graphical user interface (GUI)

2. Supports unlimited bake process programs/program steps per recipe

3. 0.1 second step time resolution (9,999.9 seconds maximum step time)

4. Temperature data logging

5. Three automated bake methods: contact, vacuum,proximity (N2 or lift pins)

6. Bake plate auto-sizing for 2″, 3″, 100mm, 150mm, and 200mm substrates

7. height programmed in 0.1 increments with an overall range of 0-30mm

8. Up/download process parameters via native USB and Ethernet ports
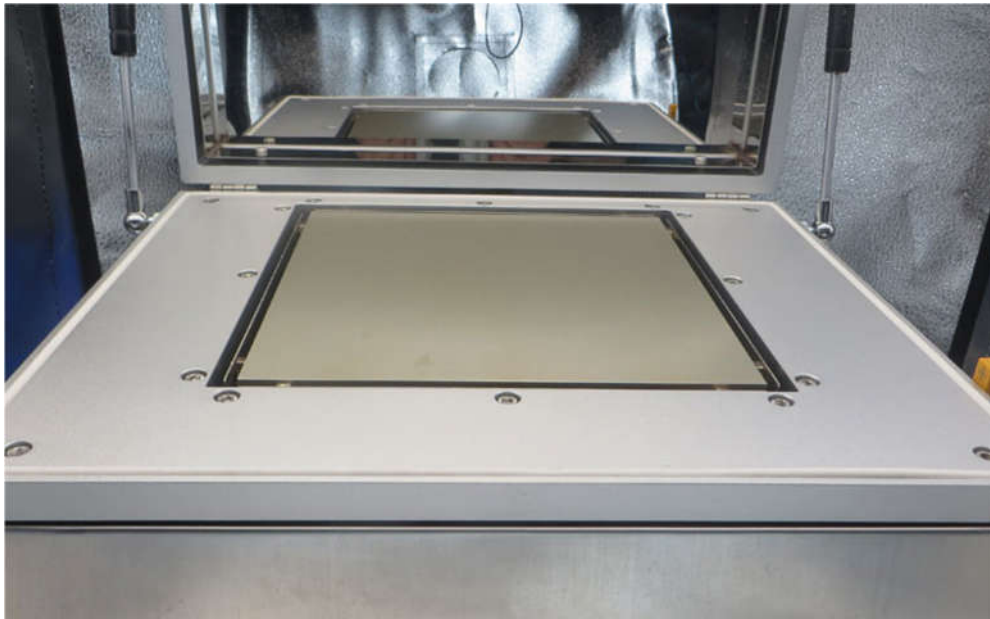
四：PRECISION

1. Substrate sizes of <10mm to 200mm round; 8" x 8" square

2. Temperature resolution: 0.1°C

3. Temperature range: ambient to 400°C (500°C/600°C/800°C optional)

4. Temperature uniformity: ±1-2% across working surface

[caption id="attachment_18525" align="aligncenter" width="750"]
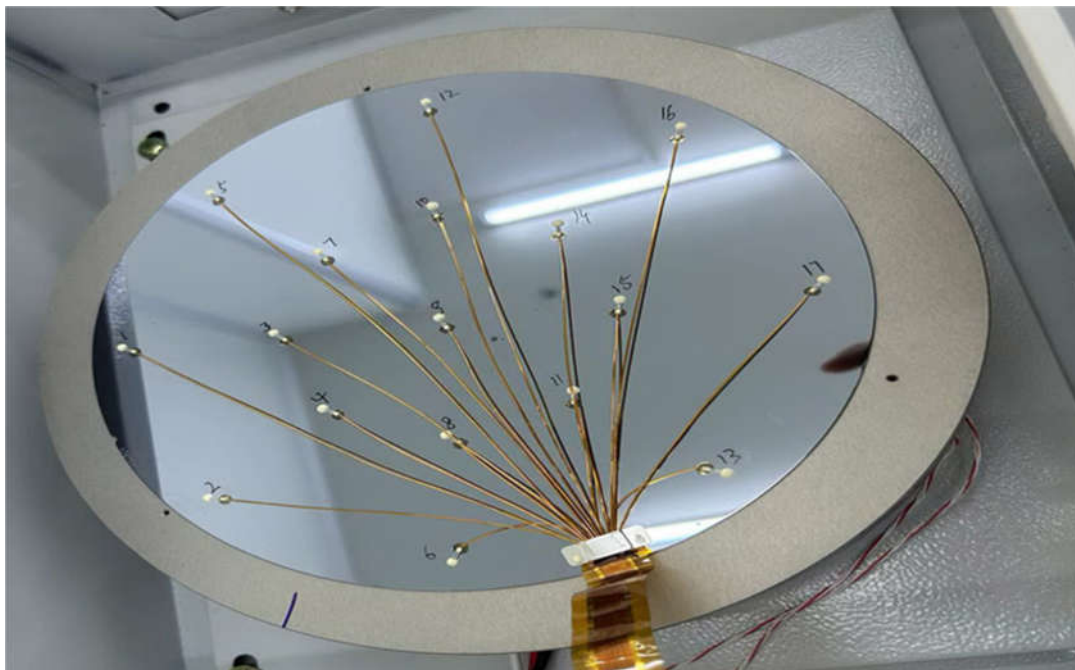
Semiconductor wafer bake plates[/caption]
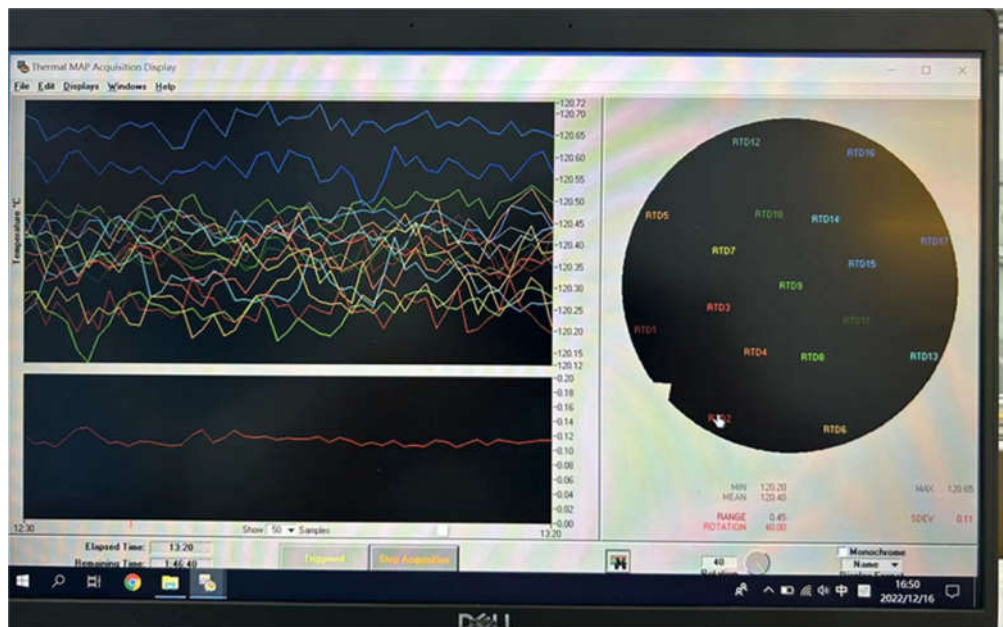
五：RELIABILITY

Industry leading uptime

1-year full warranty on parts and labor

Complimentary remote technical support for the life of the

Specifications

Utilities

- voltage ranges： 100-120; 208-230 VAC

- power requirements:1800W (13.3A); 1513W (6.6A) max

- exhaust port: 2" OD

- vacuum:<33kPaabs

- exhaus: 5-10cfm

- N2:35psi

Specifications

Temperature/Electrical	
Platinum RTD	100 Ω at zero mounted in the heater top

Temperature/Electrical	
Range	10 °C to 350 °C on the plate surface
Readability	1 °C
Temperature control type	PID
Temperature stability	1 °C
Temperature Uniformity	Better than 1% of setting from center to within 0.75" of plate edge
Heater power	1800 W
VAC	115 VAC, 50/60 Hz (230 VAC available upon request)
Fused	Yes
Line Cord	Detachable, 6 ft (1.8 m), 3-wire grounded. Single phase
Dimensions: Heater Module	
Width	18.89in(480mm) circle
Height	15.74in (400mm)
Weight	35 kg

Applications

Cleaning silicon wafers

Drying silicon wafers

Etching silicon wafers

Heat testing circuits

Heat testing epoxies

Soldering surface mount PCB's

Life cycle testing of PCB's

Testing LCD's

Applicable to a variety of fields

Widely used in electronics, electrical appliances, automotive, mechanical equipment, etc.

01 Semiconductor Equipment	02 Mechanical components	03 Automotive Accessories	04 Photovoltaic equipment
SEMICONDUCTOR EQUIPMENT	MECHANICAL COMPONENTS	AUTOMOTIVE PARTS	PHOTOVOLTAIC EQUIPMENT

Bake Plates are your ultimate solution for precision,
Specifications. thermal processing of semiconductor substrates. Designed
with cuttingedge technology, our bake plates ensure unparalleled,
track-quality